Molding Type Module IGBT, 2 in 1 Package, 1200 V, 100 A



INT-A-PAK

PRODUCT SUMMARY					
V _{CES}	1200 V				
I _C at T _C = 80 °C	100 A				
$V_{CE(on)}$ (typical) at $I_C = 100 \text{ A}, 25 ^{\circ}\text{C}$	1.80 V				
Speed	8 kHz to 30 kHz				
Package	INT-A-PAK				
Circuit	Half bridge				

FEATURES

- High short circuit capability, self limiting to 6 x I_C
- 10 µs short circuit capability
- V_{CE(on)} with positive temperature coefficient
- Maximum junction temperature 150 °C
- Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

TYPICAL APPLICATIONS

- AC inverter drives
- Switching mode power supplies
- Electronic welders

DESCRIPTION

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V _{CES}		1200	V
Gate to emitter voltage	V_{GES}		± 20	V
Collector current		T _C = 25 °C	200	
Collector current	IC	T _C = 80 °C	100	
Pulsed collector current	I _{CM} ⁽¹⁾	t _p = 1 ms	200	Α
Diode continuous forward current	I _F		100	
Diode maximum forward current	I _{FM}		200	
Maximum power dissipation	P_{D}	T _J = 150 °C	650	W
Short circuit withstand time	t _{SC}	T _J = 125 °C	10	μs
RMS isolation voltage	V _{ISOL}	f = 50 Hz, t = 1 min	2500	V
l ² t-value, diode	l ² t	$V_R = 0 \text{ V}, \text{ t} = 10 \text{ ms}, T_J = 125 ^{\circ}\text{C}$	1050	A ² s

Note

⁽¹⁾ Repetitive rating: pulse width limited by maximum junction temperature.

IGBT ELECTRICAL SPECIFICATIONS (T _C = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V _{(BR)CES}	$V_{GE} = 0 \text{ V}, I_{C} = 1.0 \text{ mA}, T_{J} = 25 \text{ °C}$	1200	-	-	
Collector to emitter voltage	V	$V_{GE} = 15 \text{ V}, I_{C} = 100 \text{ A}, T_{J} = 25 \text{ °C}$	-	1.80	2.20	\/
Collector to entitler voltage	V _{CE(on)}	V _{GE} = 15 V, I _C = 100 A, T _J = 125 °C	-	2.05	-]
Gate to emitter threshold voltage	V _{GE(th)}	$V_{CE} = V_{GE}$, $I_C = 4.0$ mA, $T_J = 25$ °C	5.0	6.2	7.0	
Collector cut-off current	I _{CES}	$V_{CE} = V_{CES}$, $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	5.0	mA
Gate to emitter leakage current	I _{GES}	$V_{GE} = V_{GES}$, $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA



PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t _{d(on)}		-	279	-	ns mJ
Rise time	t _r		-	61	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, I_{C} = 100 \text{ A}, R_{q} = 5.6 \Omega,$	-	308	-	
Fall time	t _f	V _{GE} = ± 15 V, T _J = 25 °C	-	205	-	
Turn-on switching loss	E _{on}		-	5.56	-	
Turn-off switching loss	E _{off}		-	6.95	-	
Turn-on delay time	t _{d(on)}		-	287	-	- ns
Rise time	t _r		-	63	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, I_{C} = 100 \text{ A}, R_{g} = 5.6 \Omega, V_{GE} = \pm 15 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$	-	328	-	
Fall time	t _f		-	360	-	
Turn-on switching loss	E _{on}		-	7.85	-	m l
Turn-off switching loss	E _{off}		-	10.55	-	- mJ
Input capacitance	C _{ies}		-	7.43	-	
Output capacitance	C _{oes}	$V_{GE} = 0 \text{ V}, V_{CE} = 25 \text{ V}, f = 1.0 \text{ MHz},$ $T_{J} = 25 \text{ °C}$	-	0.52	-	nF
Reverse transfer capacitance	C _{res}	- 1j - 20 0	-	0.34	-	
SC data	I _{SC}	$t_{SC} \leq 10~\mu s,~V_{GE} = 15~V,~T_{J} = 125~^{\circ}C,\\ V_{CC} = 900~V,~V_{CEM} \leq 1200~V$	-	470	-	Α
Internal gate resistance	R _{gint}		-	2	-	Ω
Stray inductance	L _{CE}		-	-	30	nΗ
Module lead resistance, terminal to chip	R _{CC'+EE'}	T _C = 25 °C	-	0.75	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS (T _C = 25 °C unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Diode forward voltage	V	I _F = 100 A	$T_J = 25 ^{\circ}C$	ı	1.90	2.30	V	
Diode forward voltage	V _F		T _J = 125 °C	-	2.00	-		
Diode reverse recovery charge	Q _{rr}		T _J = 25 °C	-	5.52	-		
Diode reverse recovery charge			T _J = 125 °C	-	11.88	-	μC	
Diada naak waxayaa waaayaw, ayyyaat			$I_F = 100 \text{ A}, V_R = 600 \text{ V},$	T _J = 25 °C	-	85	-	^
Diode peak reverse recovery current		$dI_F/dt = -2000 \text{ A/}\mu\text{s},$ $V_{GF} = -15 \text{ V}$	T _J = 125 °C	-	103	-	A	
Diada rayaraa raaayary anaray	_	E _{rec} -	T _J = 25 °C	-	2.06	-	mJ	
Diode reverse recovery energy	⊏ _{rec}		T _J = 125 °C	-	5.56	-	IIIJ	

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature	TJ		-	-	150	°C
Storage temperature range	T _{STG}		-40	-	125	
IGBT (per 1/2 module)	В		-	-	0.19	
Junction to case Diode (per 1/2 module)	- R _{thJC}		-	-	0.28	K/W
Case to sink	R _{thCS}	Conductive grease applied	-	0.05	-	
Maunting torque		Power terminal screw: M5		2.5 to 5.0		Nima
Mounting torque		Mounting screw: M6		3.0 to 5.0		Nm
Weight of module				150		g



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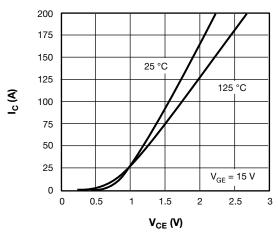
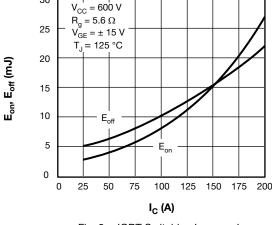


Fig. 1 - IGBT Typical Output Characteristics



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Fig. 3 - IGBT Switching Loss vs. I_C

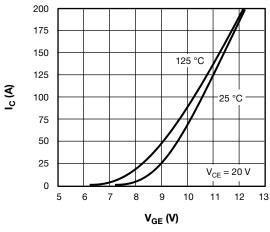


Fig. 2 - IGBT Typical Transfer Characteristics

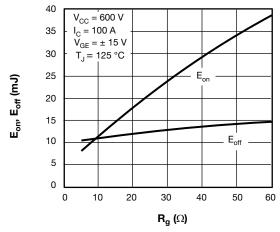


Fig. 4 - IGBT Switching Loss vs. R_a

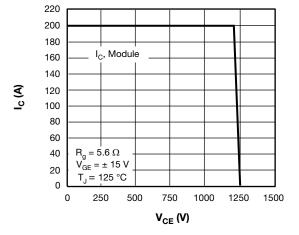


Fig. 5 - RBSOA

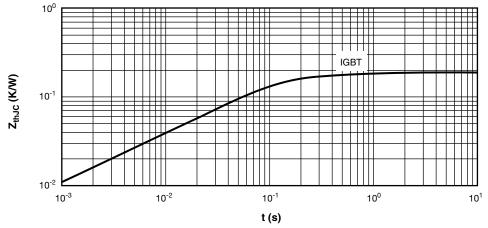


Fig. 6 - IGBT Transient Thermal Impedance

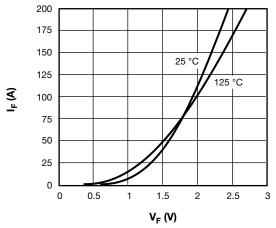


Fig. 7 - Diode Forward Characteristics

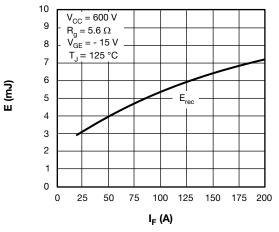


Fig. 8 - Diode Switching Loss vs. I_C

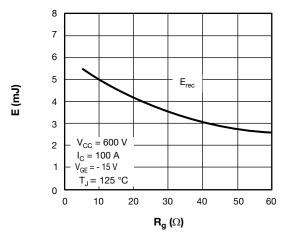


Fig. 9 - Diode Switching Loss vs. $R_{\rm g}$

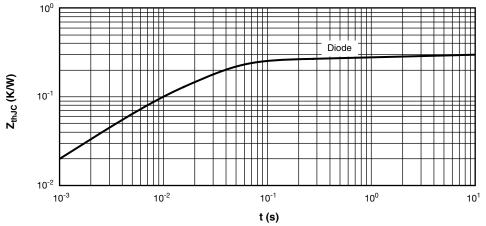
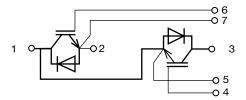


Fig. 10 - Diode Transient Thermal Impedance

CIRCUIT CONFIGURATION



LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95524			



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